

ON Semiconductor				10/15/2019
Base Part		FAN3121T_F085	HF	Pb-free
Orderable Part		FAN3121TMX-F085	Total weight (mg)	80.792
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	2.16	Silicon (Si)	7440-21-3	100
Die Attach	1.144	Silver (Ag)	7440-22-4	74
		Phenolic Resin-2	54208-63-8	26
Lead Frame	31.571	Silver (Ag)	7440-22-4	0.02217225
		Zinc (Zn)	7440-66-6	0.12353109
		Palladium (Pd)	7440-05-3	0.04751196
		Nickel (Ni)	7440-02-0	1.27965538
		Gold (Au)	7440-57-5	0.02850717
		Iron (Fe)	7439-89-6	2.31858351
		Copper (Cu)	7440-50-8	96.09768458
		Phosphorus (P)	7723-14-0	0.08235406
Mold Compound-Black	45.29	Ortho Cresol Novolac Resin	29690-82-2	6.24862
		Carbon Black (C)	1333-86-4	0.19871936
		Silica (SiO2)	14464-46-1	87.03908147
		Phenolic Resin (Novolac)	9003-35-4	6.51357916
Wire Bond - Au	0.627	Gold (Au)	7440-57-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels of dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				